

GPB30M

SINTERED GLASS JUNCTION PLASTIC RECTIFIER

VOLTAGE: 1000V

CURRENT: 3.0A

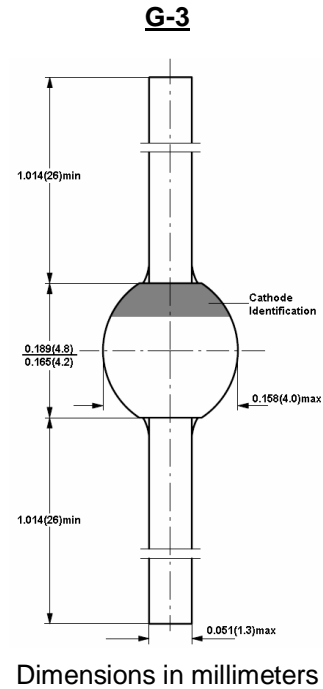


FEATURE

High temperature metallurgically bonded construction
Sintered glass cavity free junction
Capability of meeting environmental standard of MIL-S-19500
High temperature soldering guaranteed
350°C /10sec/0.375"lead length at 5 lbs tension
Operate at Ta =55°C with no thermal run away
Typical Ir<0.1μA

MECHANICAL DATA

Terminal: Plated axial leads solderable per MIL-STD 202E, method 208C
Case: Molded with UL-94 Class V-0 recognized Flame Retardant Epoxy
Polarity: color band denotes cathode
Mounting position: any



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

(single-phase, half-wave, 60HZ, resistive or inductive load rating at 25°C, unless otherwise stated, for capacitive load, derate current by 20%)

	SYMBOL	GPB30M	units
Maximum Recurrent Peak Reverse Voltage	Vrrm	1000	V
Maximum RMS Voltage	Vrms	700	V
Maximum DC blocking Voltage	Vdc	1000	V
Maximum Average Forward Rectified Current 3/8"lead length at Ta =55°C	If(av)	3.0	A
Peak Forward Surge Current 8.3ms single Half sine-wave superimposed on rated load	Ifsm	80.0	A
Maximum Instantaneous Forward Voltage at 9.0A	Vf	1.2	V
Maximum Full Load Reverse Current Full Cycle Average at 55°C	Ir(av)	100.0	μA
Maximum DC Reverse Current at rated DC blocking voltage	Ir	1.0 100.0	μA
Typical Reverse Recovery Time (Note 1)	Trr	2.0	μS
Typical Junction Capacitance (Note 2)	Cj	40.0	pF
Typical Thermal Resistance (Note 3)	Rth(ja)	20.0	°C/W
Storage and Operating Junction Temperature	Tstg, Tj	-65 to +175	°C

Note:

1. Reverse Recovery Condition If =0.5A, Ir =1.0A, Irr =0.25A
2. Measured at 1.0 MHz and applied reverse voltage of 4.0Vdc
3. Thermal Resistance from Junction to Ambient at 3/8"lead length, P.C. Board Mounted

RATINGS AND CHARACTERISTIC CURVES GPB30M

FIG. 1 - FORWARD CURRENT DERATING CURVE

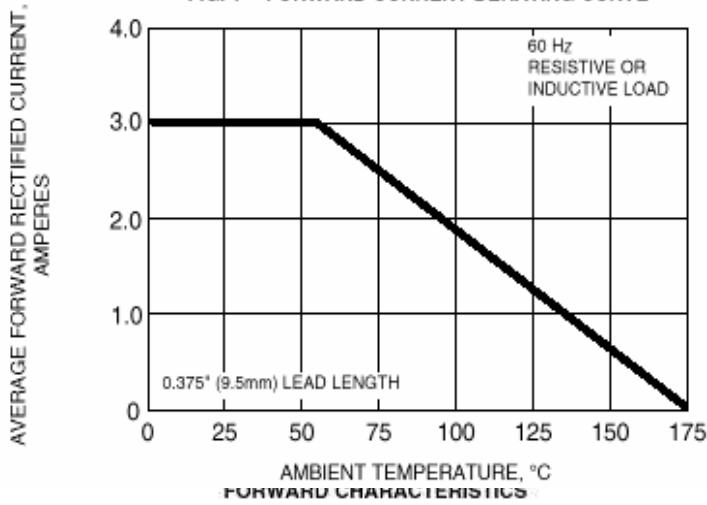


FIG. 2 - MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

